



**Product / Package Information**

Package	SOIC_W
Body Size	300 mils
Lead Count	16
Terminal Finish	100Sn
MS Number	MS011040B

**Environmental Compliance Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.61 E-01	87.3	873000	57.96	579613
Thermosets	Phenol Resin	Proprietary	1.35 E-02	4.5	45000	2.99	29877
Thermosets	Epoxy Resin 1	Proprietary	8.98 E-03	3.0	30000	1.99	19918
Thermosets	Epoxy Resin 2	Proprietary	8.98 E-03	3.0	30000	1.99	19918
Others	Others	Proprietary	5.99 E-03	2.0	20000	1.33	13279
Other inorganic materials	Carbon Black	1333-86-4	5.99 E-04	0.2	2000	0.13	1328
Subtotal			2.99 E-01	100.0	1000000	66.39	663933

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.37 E-01	97.5	975000	30.29	302906
Copper & its alloys	Iron	7439-89-6	3.29 E-03	2.35	23500	0.73	7301
Copper & its alloys	Zinc	7440-66-6	1.68 E-04	0.12	1200	0.04	373
Copper & its alloys	Phosphorus	7723-14-0	4.20 E-05	0.03	300	0.01	93
Subtotal			1.40 E-01	100	1000000	31.07	310673

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.42 E-03	100	1000000	0.31	3138

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.04 E-03	100	1000000	1.12	11173

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.00 E-04	99.99	1000000	0.11	1108

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.99 E-03	100	1000000	0.88	8845

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.93 E-04	77.00	770000	0.09	871
Other organic materials	Acrylic resin	Proprietary	3.57 E-05	7.00	70000	0.01	79
Other organic materials	Acrylate	Proprietary	2.80 E-05	5.50	55000	0.006	62
Other organic materials	Polybutadiene derivative	Proprietary	2.29 E-05	4.5	45000	0.005	51
Other organic materials	Epoxy resin	Proprietary	1.27 E-05	2.5	25000	0.003	28
Other organic materials	Butadiene Copolymer	Proprietary	7.65 E-06	1.5	15000	0.002	17
Others	Additive	Proprietary	7.65 E-06	1.5	15000	0.002	17
Others	Peroxide	Proprietary	2.55 E-06	0.5	5000	0.001	6
Subtotal			5.10 E-04	100	1000000	0.11	1131

<b>Package Totals</b>	<b>Weight (g)</b>	<b>4.51 E-01</b>	<b>Percentage (%)</b>	<b>100</b>	<b>PPM</b>	<b>1000000</b>
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary



**Product / Package Information**

Package	SOIC_W
Body Size	300 mils
Lead Count	16
Terminal Finish	SnPb
MS Number	MS011562A

**Environmental Compliance Information**

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

Molding Compound								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Other inorganic materials	Silica	60676-86-0	2.63 E-01	87.7	877000	58.23		582269
Thermosets	Epoxy Resin	Proprietary	1.50 E-02	5.0	50000	3.32		33197
Thermosets	Phenol Resin	Proprietary	1.50 E-02	5.0	50000	3.32		33197
Thermosets	Epoxy Cresol Novolac	29690-82-2	5.99 E-03	2.0	20000	1.33		13279
Other inorganic materials	Carbon Black	1333-86-3	8.98 E-04	0.3	3000	0.20		1992
Subtotal			2.99 E-01	100	1000000	66.39		663933

Leadframe								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Copper & its alloys	Copper	7440-50-8	1.37 E-01	97.5	975000	30.29		302906
Copper & its alloys	Iron	7439-89-6	3.29 E-03	2.35	23500	0.73		7301
Copper & its alloys	Zinc	7440-66-6	1.68 E-04	0.12	1200	0.04		373
Copper & its alloys	Phosphorus	7723-14-0	4.20 E-05	0.03	300	0.01		93
Subtotal			1.40 E-01	100.00	1000000	31.07		310673

Internal Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Precious metals	Silver	7440-22-4	1.42 E-03	100.0	1000000	0.31		3138

External Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Tin & its alloys	Tin	7440-31-5	4.28 E-03	85.0	850000	0.95		9497
Tin & its alloys	Lead	7439-92-1	7.56 E-04	15.0	150000	0.17		1676
Subtotal			5.04 E-03	100.0	1000000	1.12		11173

Bond Wires								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Precious metals	Gold	7440-57-5	5.00 E-04	99.99	1000000	0.11		1108

Chip								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.99 E-03	100.0	1000000	0.88		8845

Die Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	PPM
Precious metals	Silver	7440-22-4	4.08 E-04	80	800000	0.09		904
Thermosets	Epoxy Resin	Proprietary	7.65 E-05	15	150000	0.02		170
Others	Curing agent & hardener	Proprietary	2.55 E-05	5	50000	0.01		57
Subtotal			5.10 E-04	100	1000000	0.11		1131

<b>Package Totals</b>			<b>Weight (g)</b>			<b>Percentage (%)</b>		<b>PPM</b>
			4.51 E-01			100.00		1000000

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